



Eight Bit Flash Memory Card (Intel based) 512KB, 1, 2, 4 and 8 MEGABYTE

General Description

The FEA Econo Flash card series offers a low cost and high performance eight bit linear Flash solid state storage solution for code/data storage and embedded applications.

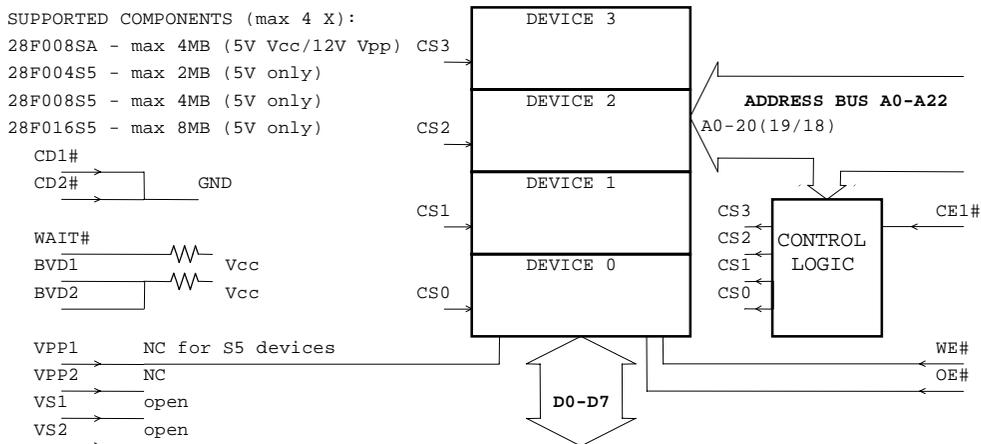
Packaged in PCMCIA type I or a type I half-card housing, the FEA card series is based on Intel/Sharp Flash memory devices: 28F0004S5 (4Mb), 28F0008S5 (8Mb) or 28F016S5 (16Mb) for 5V only applications and 28F008SA (8Mb) for 5V/12V applications. Device codes are A7h, A6h, AAh, and A2h respectively. Systems should be able to recognize all codes. The PC Card form factor offers an industry standard pinout and mechanical outline, allowing density upgrades without system design changes.

The FEA card series is designed as a simple x8 linear array of Flash devices. The 512KB density cards are built with 4 Mb components (5V only), 2MB and 4MB density options may be built with either 8Mb or 16Mb components, and the 8MB density cards are built with 16Mb components. All components have uniform 64Kbyte sectors and use identical embedded automated write and erase algorithms. The 8 bit design provides very low power operation as only one component is active at a time. The Intel Flash components provide very low standby current in Sleep Mode.

Features

- Low cost Linear Flash Card
- Single 5 Volt Supply (S5 devices) or 5V Vcc / 12V Vpp (SA devices)
- Based on Intel/Sharp Flash Components - very low power in Sleep Mode
- Fast Read Performance - 100ns or 150ns Maximum Access Time
- x8 Data Interface
- High Performance Random Writes - 10µs Typical Byte Write Time
- Automated Write and Erase Algorithms - Intel Command Set
- 50µA Typical Power-Down
- 100,000 Erase Cycles per Block
- 64K word symmetrical Block Architecture
- PC Card Standard Type I Form Factor

Block Diagram





Pinout

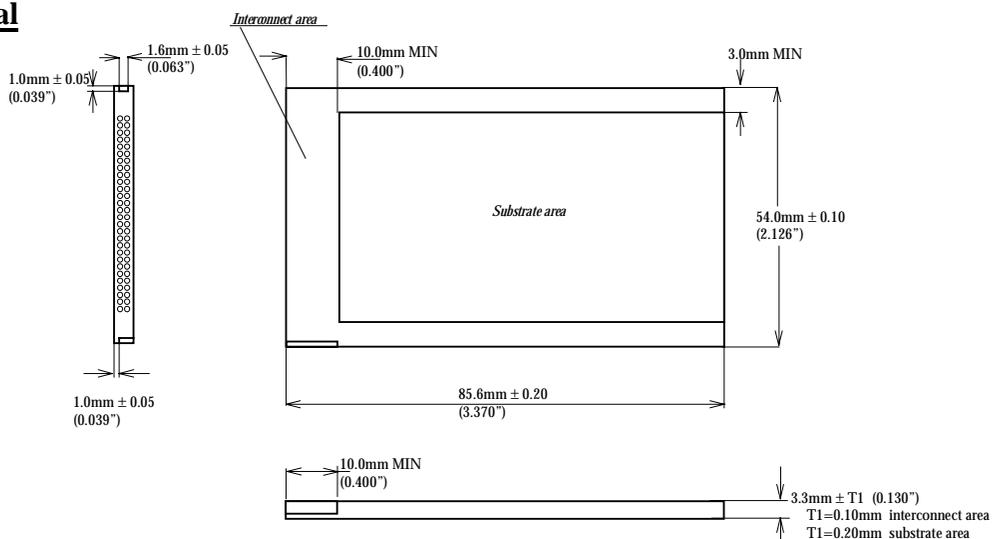
Pin	Signal name	I/O	Function	Active
1	GND		Ground	
2	DQ3	I/O	Data bit 3	
3	DQ4	I/O	Data bit 4	
4	DQ5	I/O	Data bit 5	
5	DQ6	I/O	Data bit 6	
6	DQ7	I/O	Data bit 7	
7	CE1#	I	Card enable 1	LOW
8	A10	I	Address bit 10	
9	OE#	I	Output enable	LOW
10	A11	I	Address bit 11	
11	A9	I	Address bit 9	
12	A8	I	Address bit 8	
13	A13	I	Address bit 13	
14	A14	I	Address bit 14	
15	WE#	I	Write Enable	LOW
16	RDY/BSY#	O	Ready/Busy	N.C.
17	Vcc		Supply Voltage	
18	Vpp1		12VProg. Voltage	¹⁾
19	A16	I	Address bit 16	
20	A15	I	Address bit 15	
21	A12	I	Address bit 12	
22	A7	I	Address bit 7	
23	A6	I	Address bit 6	
24	A5	I	Address bit 5	
25	A4	I	Address bit 4	
26	A3	I	Address bit 3	
27	A2	I	Address bit 2	
28	A1	I	Address bit 1	
29	A0	I	Address bit 0	
30	DQ0	I/O	Data bit 0	
31	DQ1	I/O	Data bit 1	
32	DQ2	I/O	Data bit 2	
33	WP	O	Write Protect	²⁾
34	GND		Ground	

Pin	Signal name	I/O	Function	Active
35	GND		Ground	
36	CD1#	O	Card Detect 1	LOW
37	DQ11	I/O	Data bit 11	N.C.
38	DQ12	I/O	Data bit 12	N.C.
39	DQ13	I/O	Data bit 13	N.C.
40	DQ14	I/O	Data bit 14	N.C.
41	DQ15	I	Data bit 15	N.C.
42	CE2#	I	Card Enable 2	N.C.
43	VS1	O	Voltage Sense 1	N.C.
44	RFU		Reserved	
45	RFU		Reserved	
46	A17	I	Address bit 17	
47	A18	I	Address bit 18	512KB ³⁾
48	A19	I	Address bit 19	1MB ³⁾
49	A20	I	Address bit 20	2MB ³⁾
50	A21	I	Address bit 21	4MB ³⁾
51	Vcc		Supply Voltage	
52	Vpp2		12V Prog. Voltage	N.C.
53	A22	I	Address bit 22	8MB ³⁾
54	A23	I	Address bit 23	N.C.
55	A24	I	Address bit 24	N.C.
56	A25	I	Address bit 25	N.C.
57	VS2	O	Voltage Sense 2	N.C.
58	RST	I	Card Reset	N.C.
59	Wait#	O	Extended Bus cycle	N.C.
60	RFU		Reserved	
61	REG#	I	Attrib Mem Select	N.C.
62	BVD2	O	Bat. Volt. Detect 2	
63	BVD1	O	Bat. Volt. Detect 1	
64	DQ8	I/O	Data bit 8	N.C.
65	DQ9	I/O	Data bit 9	N.C.
66	DQ10	O	Data bit 10	N.C.
67	CD2#	O	Card Detect 2	LOW
68	GND		Ground	

Notes:

1. Vpp1 connected only for versions with 28F008SA devices.
2. Connected to GND - no write protection.
3. Shows density for which specified address bit is MSB. Higher order addresses are not connected (i.e. for 4MB card A21 is MSB, A22-A25 are N.C.).

Mechanical





Card Signal Description

Symbol	Type	Name and Function
A0 - A25	INPUT	ADDRESS INPUTS: A0 through A25 enable direct addressing of up to 64MB of memory on the card. The memory will wrap at the card density boundary. The system should not try to access memory beyond the card density. The upper addresses are not connected.
DQ0 – DQ15	INPUT/OUT	DATA INPUT/OUTPUT: DQ0 THROUGH DQ15 constitute the bi-directional databus. DQ0 - DQ7 constitute the lower (even) byte. DQ8 – DQ15 are not connected. DQ7 is the MSB.
CE1#, CE2#	INPUT	CARD ENABLE 1 AND 2: CE1# enables even byte accesses, CE2# enables odd byte accesses. CE2# is not connected.
OE#	INPUT	OUTPUT ENABLE: Active low signal enabling read data from the memory card.
WE#	INPUT	WRITE ENABLE: Active low signal gating write data to the memory card.
RDY/BSY#	N.C.	READY/BUSY OUTPUT: Indicates status of internally timed erase or program algorithms. A high output indicates that the card is ready to accept accesses. This signal is not connected.
CD1#, CD2#	OUTPUT	CARD DETECT 1 and 2: Provide card insertion detection. These signals are connected to ground internally on the memory card. The host socket interface circuitry shall supply 10K-ohm or larger pull-up resistors on these signal pins.
WP	OUTPUT	WRITE PROTECT: This signal is pulled low internally. This signifies write protect = "off " for all cases.
VPP1		PROGRAM/ERASE POWER SUPPLY: Provides programming voltage 12.0V for lower byte (D0 – D7) memory components. VPP1 is connected only for cards with 28F008SA devices, not connected for 5V only card.
VPP2	N.C.	PROGRAM/ERASE POWER SUPPLY: Provides programming voltage 12.0V for upper byte (D8 – D15) memory components. VPP2 is not connected
VCC		CARD POWER SUPPLY: 5.0V
GND		GROUND: for all internal circuitry.
REG#	N.C.	ATTRIBUTE MEMORY SELECT: N.C. (only used with cards built with optional attribute memory).
RST	N.C	RESET: Active high signal for placing card in Power-on default state. Reset can be used as a Power-Down signal for the memory array.
WAIT#	OUTPUT	WAIT: This signal is pulled high internally for compatibility. No wait states are generated.
BVD1, BVD2	OUTPUT	BATTERY VOLTAGE DETECT: These signals are pulled high to maintain SRAM card compatibility.
VS1, VS2	OUTPUT	VOLTAGE SENSE: Notifies the host socket of the card's VCC requirements. VS1 and VS2 are open to indicate a 5V card has been inserted.
RFU		RESERVED FOR FUTURE USE
N.C.		NO INTERNAL CONNECTION TO CARD: pin may be driven or left floating

Functional Truth Table

Function Mode	/REG	/CE2	/CE1	/OE	/WE	D15-D8	D7-D0
Standby Mode	X	X	H	X	X	High-Z	High-Z
Read Low Byte Access	X	X	L	L	H	High-Z	Even-Byte
Write Low Byte Access	X	X	L	H	L	X	Even-Byte



DC Characteristics ⁽¹⁾

Symbol	Parameter	Notes	Typ ⁽³⁾	Max	Units	Test Conditions
ICCR	VCC Read Current		20	35	mA	VCC = 5.25V tcycle = 125ns
ICCW	VCC Program Current	S5 components		75	mA	
		SA components	10	30	mA	
IPPW	VPP Program Current	SA components	10	30	mA	VPP = VPPH
ICCE	VCC Block Erase Current	S5 components		50	mA	
		SA components	10	30	mA	
IPPE	VPP Block Erase Current	SA components	10	30	mA	
ICCS	VCC Standby Current	S5 components, 2)	50	100	μA	VCC = 5.25V
		SA components, 2)	100		μA	

CMOS Test Conditions: VIL = VSS ± 0.2V, VIH = VCC ± 0.2V

Notes:

1. All currents are RMS values unless otherwise specified.
2. Control Signals: CE1#, CE2#, OE#, WE#.
3. Typical: VCC = 5V, T = +25°C.

AC Characteristics ⁽¹⁾

VCC = 5V ± 5%, TA = 0°C to + 70°C

SYM	Parameter	100ns		150ns		Unit
		Min	Max	Min	Max	
t _C (R)	Read Cycle Time	100		150		ns
t _a (A)	Address Access Time		100		150	ns
t _a (CE)	Card Enable Access Time		100		150	ns
t _a (OE)	Output Enable Access Time		50		75	ns
t _c W	Write Cycle Time	100		150		ns
t _w (WE)	Write Pulse Width	60		80		ns

Note: AC timing diagrams and characteristics are guaranteed to meet or exceed PCMCIA 2.1 specifications.

Data Write and Erase Performance ^(1,3)

VCC = 5V ± 5%, TA = 0°C to + 70°C

SYM	Parameter	Notes	Min	Typ ⁽¹⁾	Max	Units	Test Conditions
t _{WHQV1} t _{EHQV1}	Word/Byte Program time	2		8μs	3ms		
t _{WHQV2} t _{EHQV2}	Block Program Time	2		0.4	2.1	sec	Word Program Mode
	Block Erase Time	2		0.6	10	sec	
	Full Chip Erase Time	2, 4		38.4		sec	

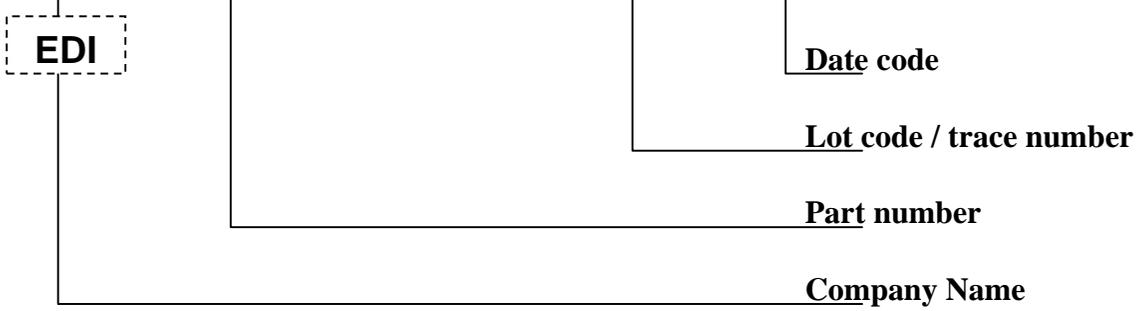
Notes:

1. Typical: Nominal voltages and TA = 25°C.
2. Excludes system overhead.
3. Valid for all speed options.
4. Chip erase time based on 8 Mbit Flash components.



PRODUCT MARKING

WED7P008FEA0500C15 C995 9915

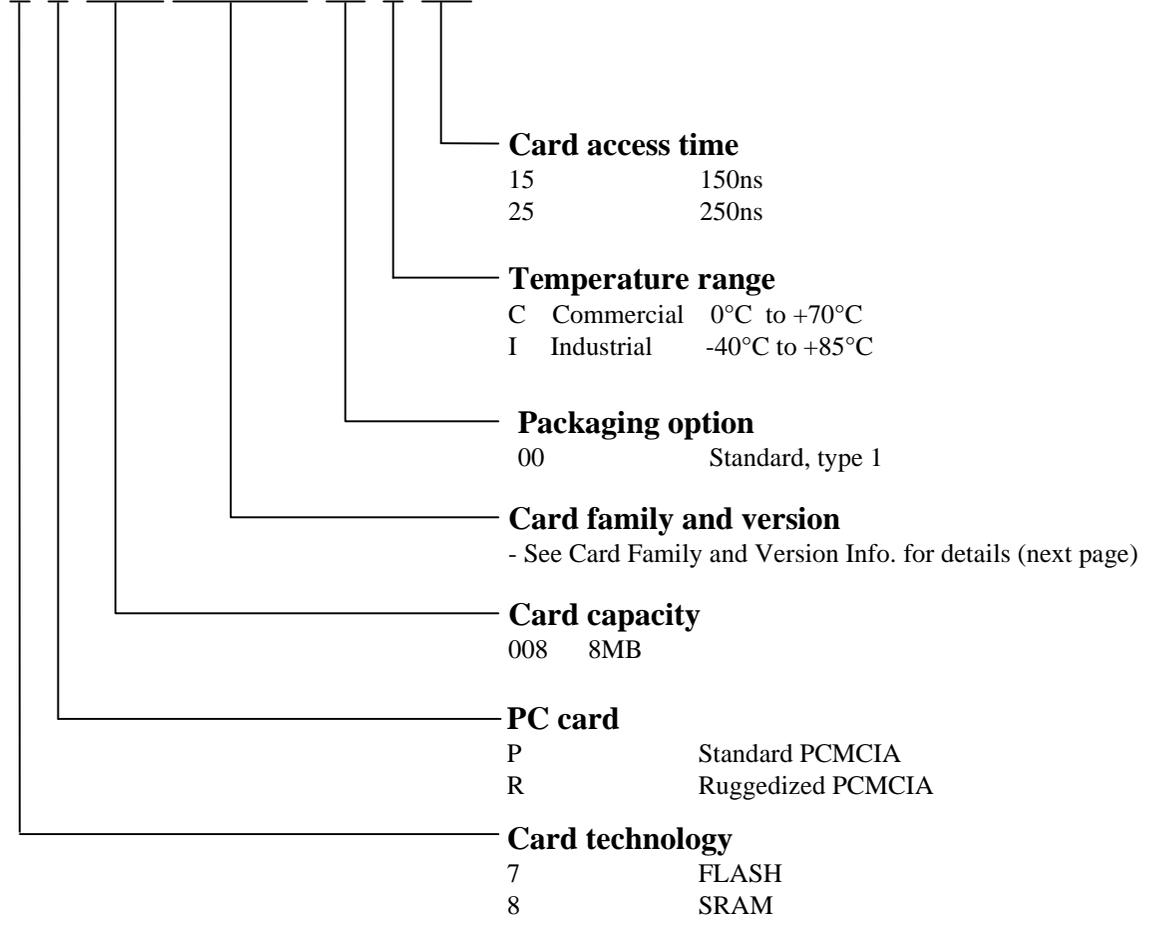


Note:

Some products are currently marked with our pre-merger company name/acronym (EDI). During our transition period, some products will also be marked with our new company name/acronym (WED). Starting October 2000 all PCMCIA products will be marked only with the WED prefix.

PART NUMBERING

7 P 008 FEA05 00 C 15



**Ordering Information**

Eight Bit Flash Memory Card

7P XXX FEA YY 00 T ZZ

where

XXX:	512	512KB (YY 01 only)
	001	1MB (YY 02, 03)
	002	2MB (YY 02, 03, 05)
	004	4MB (YY 02, 03, 05)
	008	8MB (YY 05 only)

YY:	01	28F008SA base
	02	28F004S5 base
	03	28F008S5 base
	05	28F016S5 base

T:	C	Commercial
	I	Industrial
	M	Military Temp

ZZ:	10	100ns
	15	150ns

Revision history:

<i>rev level</i>	<i>description</i>	<i>date</i>
rev 0	initial release	Feb 2, 1998
rev 1	Logo change	May 27, 1999
rev 2	added page 5	May 31, 2000
	Page Header Change	
rev 3	Corrected errors, pg. 4	August 1, 2000

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